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January 1999 Revised June 2005

74LVT16373 • 74LVTH16373 Low Voltage 16-Bit Transparent Latch with 3-STATE Outputs

General Description

The LVT16373 and LVTH16373 contain sixteen non-inverting latches with 3-STATE outputs and is intended for bus oriented applications. The device is byte controlled. The flip-flops appear transparent to the data when the Latch Enable (LE) is HIGH. When LE is LOW, the data that meets the setup time is latched. Data appears on the bus when the Output Enable $(\overline{\text{OE}})$ is LOW. When $\overline{\text{OE}}$ is HIGH, the outputs are in a high impedance state.

The LVTH16373 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs

These latches are designed for low-voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVT16373 and LVTH16373 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining a low power dissipation.

Features

- Input and output interface capability to systems at 5V V_{CC}
- Bushold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH16373), also available without bushold feature (74LVT16373)
- Live insertion/extraction permitted
- Power Up/Power Down high impedance provides glitch-free bus loading
- Outputs source/sink -32 mA/+64 mA
- Functionally compatible with the 74 series 16373
- Latch-up performance exceeds 500 mA
- ESD performance:

Human-body model > 2000V Machine model > 200V Charged-device model > 1000V

■ Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA) (Preliminary)

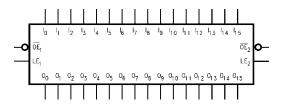
Ordering Code:

Order Number	Package Number	Package Description
74LVT16373GX (Note 1)	BGA54A (Preliminary)	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide [TAPE and REEL]
74LVT16373MEA (Note 2)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74LVT16373MTD (Note 2)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide
74LVTH16373GX (Note 1)	BGA54A (Preliminary)	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide [TAPE and REEL]
74LVTH16373MEA (Note 2)	MS48A	48-Lead Small Shrink Outline Package (SSOP), JEDEC MO-118, 0.300" Wide
74LVTH16373MTD (Note 2)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 1: BGA package available in Tape and Reel only.

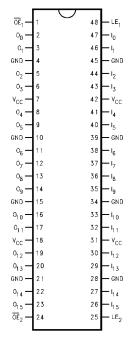
Note 2: Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Logic Symbol

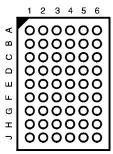


Connection Diagrams

Pin Assignment for SSOP and TSSOP



Pin Assignment for FBGA



(Top Thru View)

Pin Descriptions

Pin Names Description			
OE _n	Output Enable Input (Active LOW)		
LE _n	Latch Enable Input		
I ₀ -I ₁₅	Inputs		
O ₀ -O ₁₅	3-STATE Outputs		
O ₀ -O ₁₅ NC	No Connect		

FBGA Pin Assignments

	1	2	3	4	5	6
Α	O ₀	NC	OE ₁	LE ₁	NC	I ₀
В	O ₂	O ₁	NC	NC	I ₁	l ₂
С	O ₄	Ο ₃	V _{CC}	V _{CC}	l ₃	I ₄
D	O ₆	O ₅	GND	GND	l ₅	I ₆
E	Ο ₈	O ₇	GND	GND	I ₇	I ₈
F	O ₁₀	O ₉	GND	GND	l ₉	I ₁₀
G	O ₁₂	O ₁₁	V _{CC}	V _{CC}	I ₁₁	I ₁₂
Н	O ₁₄	O ₁₃	NC	NC	I ₁₃	I ₁₄
J	O ₁₅	NC	OE ₂	LE ₂	NC	I ₁₅

Truth Tables

	Outputs		
LE ₁	OE ₁	I ₀ –I ₇	O ₀ -O ₇
Х	Н	Х	Z
Н	L	L	L
Н	L	Н	Н
L	L	Χ	O _o

	Inputs				
LE ₂	\overline{OE}_2	I ₈ –I ₁₅	O ₈ -O ₁₅		
Х	Н	Х	Z		
Н	L	L	L		
Н	L	Н	Н		
L	L	X	Oo		

H = HIGH Voltage Level

L = LOW Voltage Level

X = Immaterial Z = HIGH Impedance

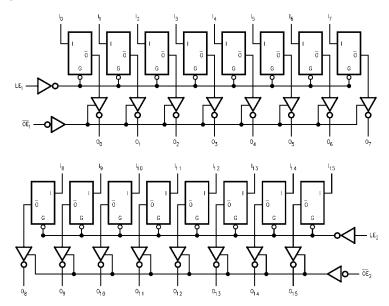
 O_0 = Previous output prior to HIGH-to-LOW transition of LE

Functional Description

The LVT16373 and LVTH16373 contain sixteen D-type latches with 3-STATE standard outputs. The device is byte controlled with each byte functioning identically, but independent of the other. Control pins can be shorted together to obtain full 16-bit operation. The following description applies to each byte. When the Latch Enable (LEn) input is HIGH, data on the $D_{\rm n}$ enters the latches. In this condition the latches are transparent, i.e, a latch output will change states each time its D input changes. When LEn is LOW,

the latches store information that was present on the D inputs a setup time preceding the HIGH-to-LOW transition of LEn. The 3-STATE standard outputs are controlled by the Output Enable (\overline{OE}_n) input. When \overline{OE}_n is LOW, the standard outputs are in the 2-state mode. When \overline{OE}_n is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the latches.

Logic Diagrams



Please note that these diagrams are provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Symbol	Parameter	Value	Conditions	Units	
V _{CC}	Supply Voltage	-0.5 to +4.6		V	
V _I	DC Input Voltage	-0.5 to +7.0		V	
Vo	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V	
		-0.5 to +7.0	Output in HIGH or LOW State (Note 4)	V	
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA	
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA	
Io	DC Output Current	64	V _O > V _{CC} Output at HIGH State	mΛ	
		128	V _O > V _{CC} Output at LOW State	mA	
I _{CC}	DC Supply Current per Supply Pin	±64		mA	
I _{GND}	DC Ground Current per Ground Pin	±128		mA	
T _{STG}	Storage Temperature	-65 to +150		°C	

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage	2.7	3.6	V
VI	Input Voltage	0	5.5	V
Гон	HIGH Level Output Current		-32	mA
I _{OL}	LOW Level Output Current		64	mA
T _A	Free-Air Operating Temperature	-40	85	°C
$\Delta t/\Delta V$	Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V	0	10	ns/V

Note 3: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

Note 4: Io Absolute Maximum Rating must be observed.

DC Electrical Characteristics

Symbol	Parameter		V _{CC}	T _A = -40°0	C to +85°C	Units	Conditions
Symbol	raiailietei		(V)	Min	Max	Onits	Conditions
V _{IK}	Input Clamp Diode Voltage		2.7		-1.2	V	I _I = -18 mA
V _{IH}	Input HIGH Voltage		2.7-3.6	2.0		V	$V_O \le 0.1V$ or
V _{IL}	Input LOW Voltage		2.7-3.6		0.8	V	V _O ≥ V _{CC} - 0.1V
V _{OH}	Output HIGH Voltage		2.7-3.6	V _{CC} - 0.2			I _{OH} = -100 μA
			2.7	2.4		V	I _{OH} = -8 mA
			3.0	2.0			$I_{OH} = -32 \text{ mA}$
V _{OL}	Output LOW Voltage		2.7		0.2		$I_{OL} = 100 \mu A$
			2.7		0.5		I _{OL} = 24 mA
			3.0		0.4	V	I _{OL} = 16 mA
			3.0		0.5		I _{OL} = 32 mA
			3.0		0.55		I _{OL} = 64 mA
I _{I(HOLD)}	Bushold Input Minimum Drive		3.0	75		μА	V _I = 0.8V
(Note 5)			3.0	-75		μА	V _I = 2.0V
I _{I(OD)}	Bushold Input Over-Drive		3.0	500		μА	(Note 6)
(Note 5)	Current to Change State		3.0	-500		μА	(Note 7)
I	Input Current		3.6		10		V _I = 5.5V
	Ī	Control Pins	3.6		±1	μА	V _I = 0V or V _{CC}
	1	Data Pins	3.6		-5	μΛ	$V_I = 0V$
		Dala FIIIS	3.0		1		$V_I = V_{CC}$
l _{OFF}	Power Off Leakage Current		0		±100	μΑ	$0V \le V_I \text{ or } V_O \le 5.5V$
I _{PU/PD}	Power Up/Down 3-STATE Output Current		0-1.5V		±100	^	V _O = 0.5V to 3.0V
			0-1.50		±100	μА	V _I = GND or V _{CC}
l _{OZL}	3-STATE Output Leakage Current		3.6		-5	μΑ	V _O = 0.5V
l _{ozh}	3-STATE Output Leakage Curre	ent	3.6		5	μА	V _O = 3.0V
I _{OZH} +	3-STATE Output Leakage Curre	ent	3.6		10	μА	$V_{CC} < V_O \le 5.5V$

DC Electrical Characteristics (Continued)

Symbol	Parameter	V _{CC}	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		Units	Conditions	
- Cymbol	T didilictor	(V)	Min	Max	Oiiiio	Conditions	
I _{CCH}	Power Supply Current	3.6		0.19	mA	Outputs HIGH	
I _{CCL}	Power Supply Current	3.6		5	mA	Outputs LOW	
I _{CCZ}	Power Supply Current	3.6		0.19	mA	Outputs Disabled	
I _{CCZ} +	Power Supply Current	3.6		0.19	mA	$V_{CC} \le V_O \le 5.5V$,	
						Outputs Disabled	
ΔI_{CC}	Increase in Power Supply Current	3.6		0.2	mA	One Input at V _{CC} – 0.6V	
	(Note 8)					Other Inputs at V _{CC} or GND	

Note 5: Applies to bushold versions only (74LVTH16373).

Note 6: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 7: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

Note 8: This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics (Note 9)

Symbol	Symbol Parameter		T _A = 25°C			Units	Conditions	
Symbol	i didiletei	(V)	Min	Min Typ Max		Oille	$C_L = 50 \text{ pF, } R_L = 500\Omega$	
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3		0.8		V	(Note 10)	
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3		-0.8		V	(Note 10)	

Note 9: Characterized in SSOP package. Guaranteed parameter, but not tested.

Note 10: Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

		T _A :				
Symbol	Parameter	V _{CC} = 3.	3V ± 0.3V	V _{CC}	Units	
		Min	Max	Min	Max	1
t _{PHL}	Propagation Delay	1.5	3.9	1.5	4.3	ns
t _{PLH}	D _n to O _n	1.5	3.8	1.5	4.2	115
t _{PHL}	Propagation Delay	1.9	4.2	1.9	4.4	ns
t _{PLH}	LE to O _n	1.6	4.3	1.6	4.8	115
t _{PZL}	Output Enable Time	1.3	4.3	1.3	4.9	
t _{PZH}		1.0	4.3	1.0	5.1	ns
t _{PLZ}	Output Disable Time	1.5	4.7	1.5	4.8	ns
t _{PHZ}		2.0	5.0	2.0	5.4	115
t _S	Setup Time, D _n to LE	1.0		0.8		ns
t _H	Hold Time, D _n to LE	1.0		1.1		ns
t _W	LE Pulse Width	3.0		3.0		ns
toshl	Output to Output Skew (Note 11)		1.0		1.0	ns
toslh			1.0		1.0	lis

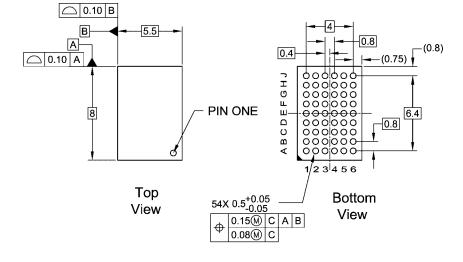
Note 11: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

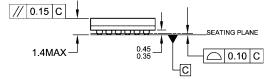
Capacitance (Note 12)

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	V _{CC} = Open, V _I = 0V or V _{CC}	4	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.0V$, $V_{O} = 0V$ or V_{CC}	8	pF

Note 12: Capacitance is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.

Physical Dimensions inches (millimeters) unless otherwise noted



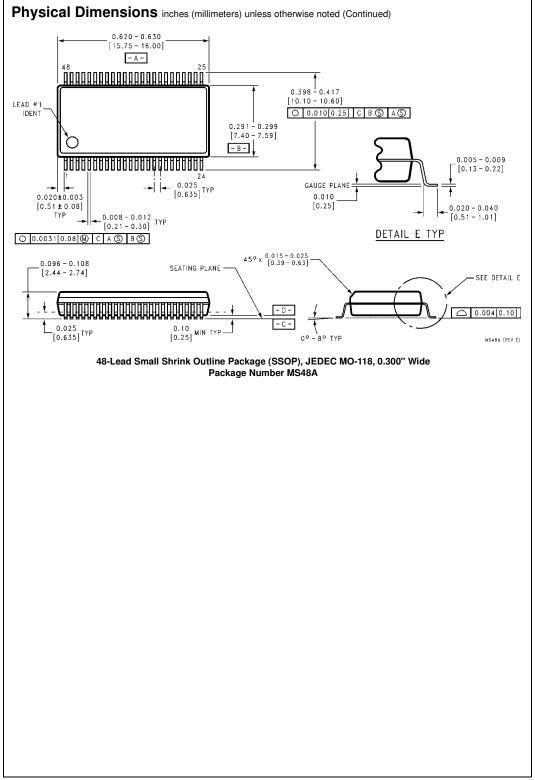


NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- **B. ALL DIMENSIONS IN MILLIMETERS**
- C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)
 .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS
 D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A Preliminary



Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-99. 9.20 8.10 50. O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION 0.1 C SEE DETAIL A 0.90+0.15 ALL LEAD TIPS 0.09-0.20 0.10±0.05 0.17-0.27 0.50 ♦ 0.13\@ A B\S C\S 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MC-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 1.00 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

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